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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
TMP6131ELPGMQ1	Active	Production	TO-92 (LPG) 2	3000 AMMO	Yes	SN	N/A for Pkg Type	-40 to 170	TMP61
TMP6131ELPGMQ1.A	Active	Production	TO-92 (LPG) 2	3000 AMMO	Yes	SN	N/A for Pkg Type	-40 to 170	TMP61
TMP6131QDECRQ1	Active	Production	X1SON (DEC) 2	10000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	EL
TMP6131QDECRQ1.A	Active	Production	X1SON (DEC) 2	10000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	EL
TMP6131QDECTQ1	Obsolete	Production	X1SON (DEC) 2	-	-	Call TI	Call TI	-40 to 125	EL
TMP6131QDYARQ1	Active	Production	SOT-5X3 (DYA) 2	3000 LARGE T&R	Yes	SN	Level-3-260C-168 HR	-40 to 150	1GK
TMP6131QDYARQ1.A	Active	Production	SOT-5X3 (DYA) 2	3000 LARGE T&R	Yes	SN	Level-3-260C-168 HR	-40 to 150	1GK
TMP6131QLPGMQ1	Active	Production	TO-92 (LPG) 2	3000 AMMO	Yes	SN	N/A for Pkg Type	-40 to 125	TMP61
TMP6131QLPGMQ1.A	Active	Production	TO-92 (LPG) 2	3000 AMMO	Yes	SN	N/A for Pkg Type	-40 to 125	TMP61

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE OPTION ADDENDUM

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and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TMP61-Q1:

Catalog: TMP61

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product